STANSON

STP3467

P Channel Enhancement Mode MOSFET

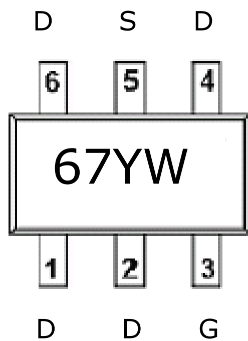
-5.2A

DESCRIPTION

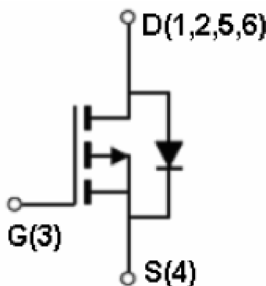
The STP3467 is the P-Channel enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

PIN CONFIGURATION

TSOP-6P



Y: Year
A: Week Code



FEATURE

- -20V/-5.0A, $R_{DS(ON)}$=90mohm@VGS=-4.5V
- -20V/-3.5A, $R_{DS(ON)}$=110mohm@VGS=-2.5V
- -20V/-1.7A, $R_{DS(ON)}$=140mohm@VGS=-1.8V

- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional an-resistance and maximum DC current capability
- TSOP-6P package design

ORDERING INFORMATION

Part Number	Package	Part Marking
STP3467ST6RG	TSOP-6	67YW

※ Week Code Code : A ~ Z ; a ~ z

※ STP3467ST6RG   ST6 : TSOP-6; R: Tape Reel ; G: Pb – Free

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ABSOULTE MAXIMUM RATINGS (Ta = 25℃ unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V_{DSS}	-20	V
Gate-Source Voltage		V_{GSS}	±12	V
Continuous Drain Current (T_J=150℃)	T_A=25℃	I_D	-5.2	A
	T_A=70℃		-4.2	
Pulsed Drain Current		I_{DM}	-20	A
Continuous Source Current (Diode Conduction)		I_S	-1.7	A
Power Dissipation	T_A=25℃	P_D	2.0	W
	T_A=70℃		1.3	
Operation Junction Temperature		T_J	-55/150	℃
Storage Temperature Range		T_{STG}	-55/150	℃
Thermal Resistance-Junction to Ambient		$R_{\theta JA}$	90	℃/W

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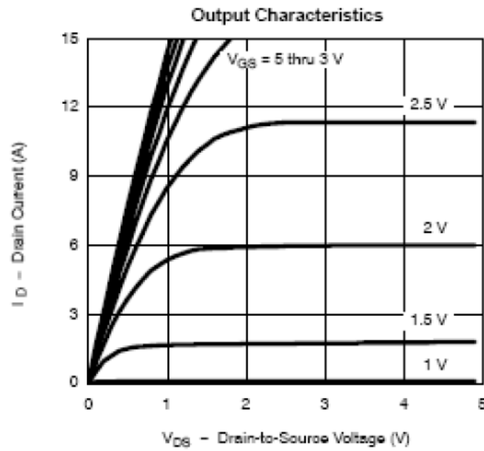
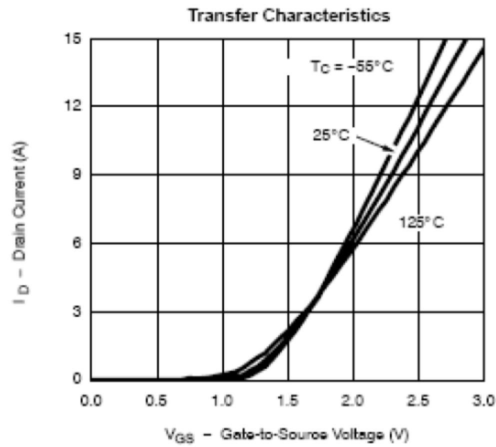
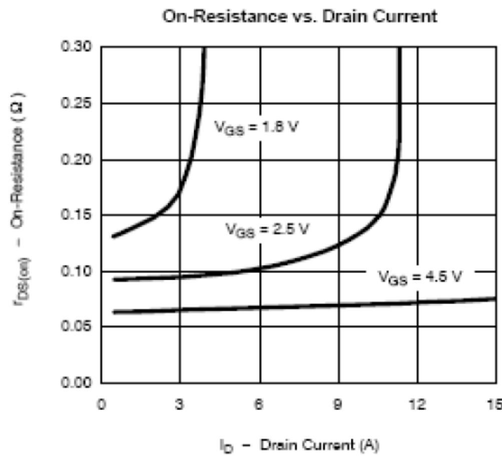
ELECTRICAL CHARACTERISTICS (Ta = 25℃ Unless otherwise noted)

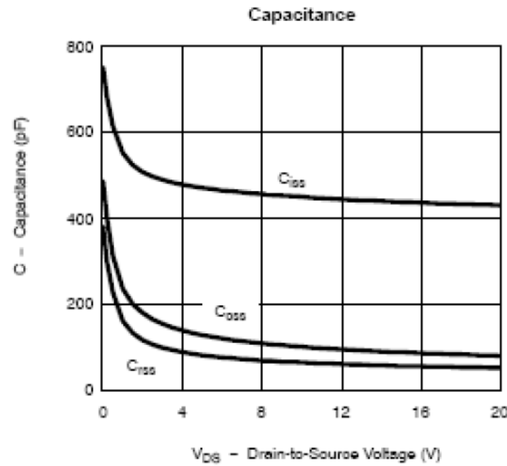
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V,I_D=-250uA	-20			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=VGS,I_D=-250uA	-0.35		-0.8	V
Gate Leakage Current	I_{GSS}	V_{DS}=0V,V_{GS}=±12V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-20V,V_{GS}=0V			-1	uA
		V_{DS}=-20V,V_{GS}=0V T_J=55℃			-5	
On-State Drain Current	$I_{D(on)}$	V_{DS}≦-5V,V_{GS}=-10V	-6			A
Drain-source On-Resistance	$R_{DS(on)}$	V_{GS}=-10V,I_D=-5.2A		0.075	0.090	Ω
		V_{GS}=-4.5V,I_D=-4.2A		0.090	0.110	
		V_{GS}=-1.8V,I_D=-1.7A		0.120	0.140	
Forward Transconductance	g_{fs}	V_{DS}=-5.0V,I_D=-2.8A		-10		S
Diode Forward Voltage	V_{SD}	I_S=-1.5A,V_{GS}=0V		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q_g	V_{DS}=-6V,V_{GS}=-4.5V, V_{DS}=-2.8A		4.8	8	nC
Gate-Source Charge	Q_{gs}			1.0		
Gate-Drain Charge	Q_{gd}			1.0		
Input Capacitance	Ciss	V_{DS}=-6V,V_{GS}=0, f=1MHz		485		pF
Output Capacitance	Coss			85		
Reverse Transfer Capacitance	Crss			40		
Turn-On Time	$T_{d(on)}$	V_{DD}=-6V, R_L=6Ω, V_{GEN}=-4.5V R_G=6Ω		10	15	ns
	t_r			15	25	
Turn-Off Time	$T_{d(off)}$			18	25	
	t_f			15	20	

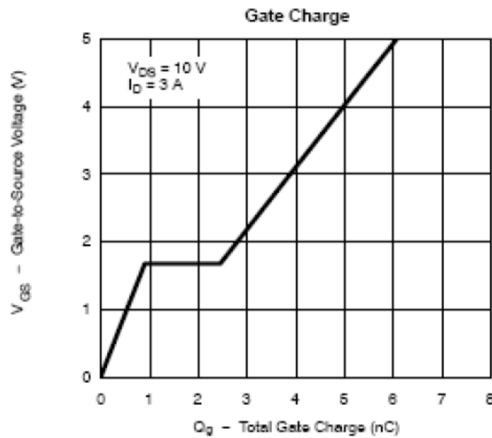
TYPICAL CHARACTERICTICS

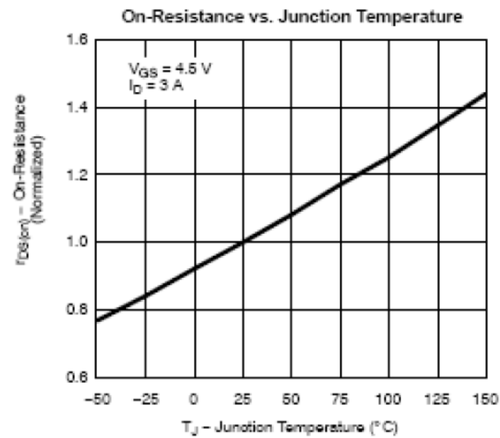












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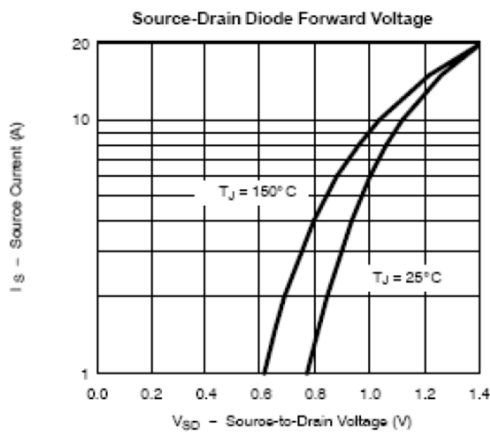
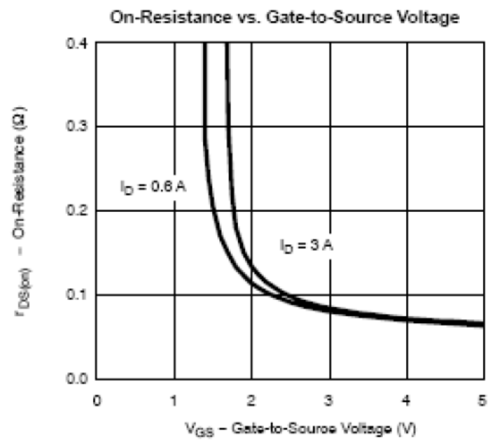
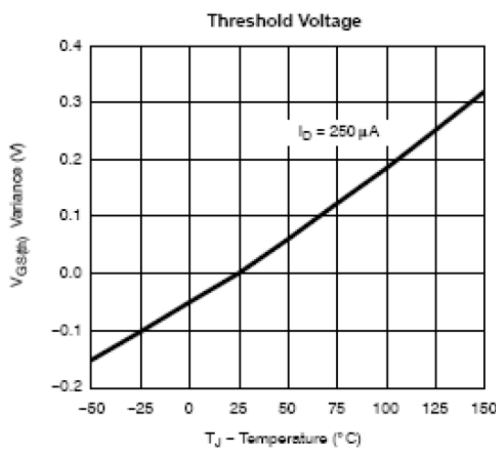
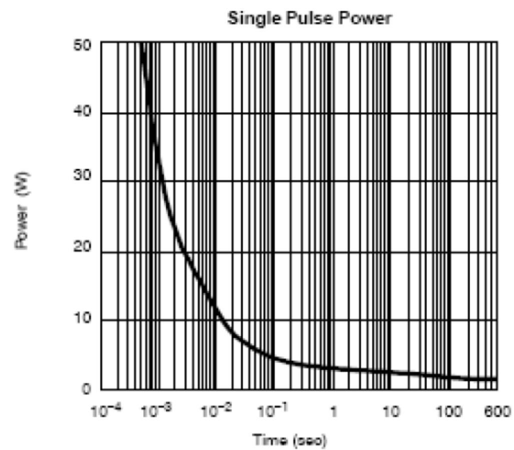
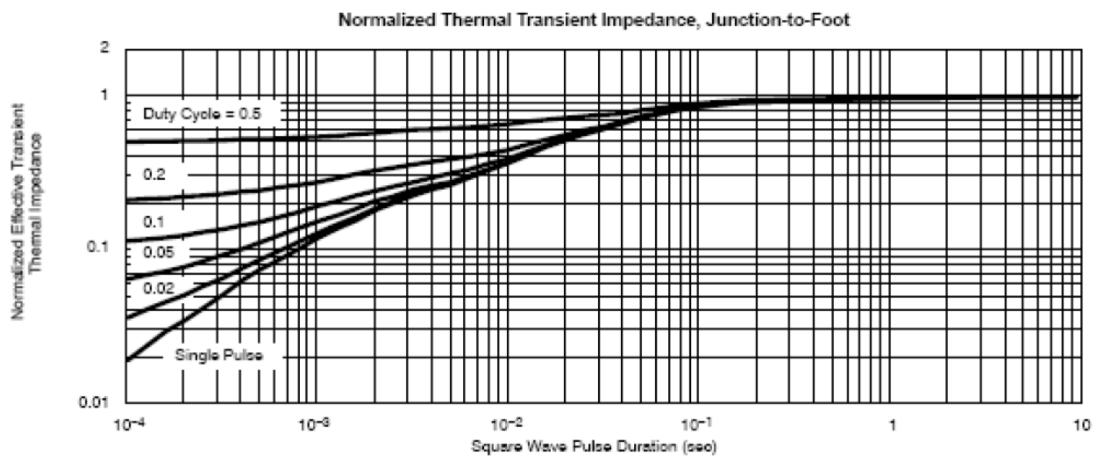


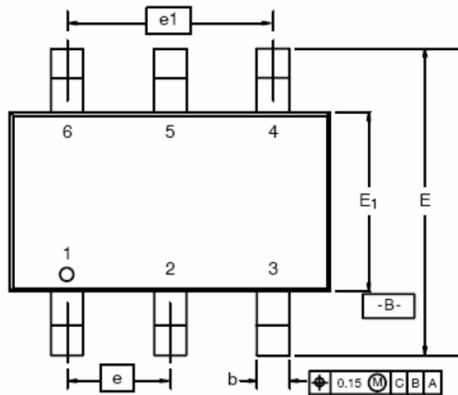


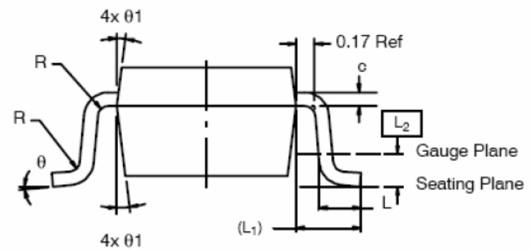






TSOP-6 PACKAGE OUTLINE





Dim	MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max
A	0.91	-	1.10	0.036	-	0.043
A_1	0.01	-	0.10	0.0004	-	0.004
A_2	0.90	-	1.00	0.035	0.038	0.039
b	0.30	0.32	0.45	0.012	0.013	0.018
c	0.10	0.15	0.20	0.004	0.006	0.008
D	2.95	3.05	3.10	0.116	0.120	0.122
E	2.70	2.85	2.98	0.106	0.112	0.117
E_1	1.55	1.65	1.70	0.061	0.065	0.067
e	1.00 BSC			0.0394 BSC		
e_1	1.90	2.00	2.10	0.075	0.080	0.085
L	0.35	-	0.50	0.014	-	0.020
L_1	0.60 Ref			0.024 Ref		
L_2	0.25 BSC			0.010 BSC		
R	0.10	-	-	0.004	-	-
θ	0°	4°	8°	0°	4°	8°
$θ_1$	7° Nom			7° Nom		